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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of
Miyazaki

Docket Number: TI-36833

Serial No.: 10/750,059

Art Unit: 2814

Filed: 12/30/2003

Examiner: Thao X Le

For: **SOLDER BALL PAD STRUCTURE**

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| NAME OF INVENTOR(S): HIROSHI MIYAZAKI | | RECEIPT DATE & SERIAL NO.: Serial No.: 10/750,059 | |
| TITLE OF INVENTION: SOLDER BALL PAD STRUCTURE | | Conf. No: 9129 | |
| TI FILE NO.: TI-36833 | DEPOSIT ACCT. NO.: 20-0668 | | |
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